

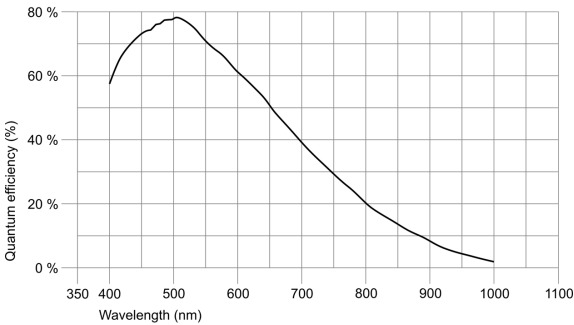
In series
The model is in series and available for the long term.



Specification

Sensor

Sensor type	CMOS Mono
Shutter	Global Shutter
Sensor characteristic	Linear
Pixel Class	2 MP
Resolution	2.35 Mpix
Resolution (h x v)	1936 x 1216 Pixel
Aspect ratio	16:10
ADC	12 bit
Color depth (camera)	12 bit
Optical sensor class	1/1.2"
Optical Size	11.345 mm x 7.126 mm
Optical sensor diagonal	13.4 mm 1/1.2"
Pixel size	5.86 μ m
CRA (Chief Ray Angle)	0 °
Manufacturer	Sony
Sensor Model	IMX249LLJ-C
Gain (master/RGB)	31.6x/-
AOI horizontal	same frame rate
AOI vertical	increased frame rate
AOI image width / step width	256 / 2
AOI image height / step width	1 / 1
AOI position grid (horizontal/vertical)	2 / 1
Binning horizontal	-
Binning vertical	-
Binning method	Horizontal: addition / Vertical: addition
Binning factor	-
Decimation (subsampling) horizontal	-
Decimation (subsampling) vertical	-
Decimation (subsampling) method	M/C automatic
Decimation (subsampling) factor	-



Model

Frame rate freerun mode	46 fps
Frame rate trigger (continuous)	47 fps
Frame rate trigger (maximum)	47 fps
Exposure time (minimum - maximum)	0.031 ms - 2000 ms
Long exposure (maximum)	90000 ms
Line rate freerun mode (line scan)	1432 1/s
Line rate trigger mode (line scan)	1545 1/s
Lines per frame (line scan)	8000
Power consumption	1.7 W - 3.1 W
Image memory	128 MB

Ambient conditions

For PCB versions, refer to the separate hints in the respective documentation.

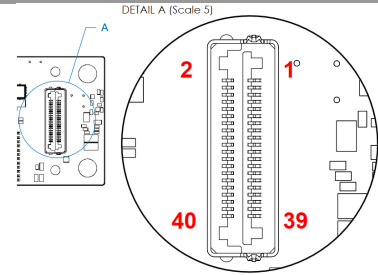
Allowed device temperature during operation	0 °C - 55 °C / 32 °F - 131 °F
Allowed device temperature during storage	-20 °C - 60 °C / -4 °F - 140 °F
Humidity (relative, non-condensing)	20 % - 80 %

Connectors

Interface connector	Samtec LSHM 40pol
I/O connector	40-pin header (Samtec LSHM-120-L2.5-L-DV-A-S-K-TR)
Power supply	12 V - 24 V

Pin assignment I/O connector

1	Input power supply (VCC) 12-24 V DC $\pm$ 10 %
2	Do not connect (for future use)
3	Input power supply (VCC) 12-24 V DC $\pm$ 10 %
4	Do not connect (for future use)
5	Ground (GND)
6	Do not connect (for future use)
7	Flash output without optocoupler 3.15 V 8 mA
8	Do not connect (for future use)
9	Trigger input without optocoupler 3.15 V
10	Ground (GND)
11	Do not connect (for future use)
12	Ground (GND)
13	Do not connect (for future use)
14	Do not connect (for future use)
15	I2C SDA (signal data) 3.15 V
16	Do not connect (for future use)
17	I2C SCL (signal clock) 3.15 V
18	Do not connect (for future use)
19	Do not connect (for future use)
20	RJ45 MX0 (-)
21	Do not connect (for future use)
22	RJ45 MX0 (+)
23	General Purpose I/O (GPIO) 2, 3.15 V 8 mA
24	Do not connect (for future use)
25	General Purpose I/O (GPIO) 1, 3.15 V 8 mA
26	RJ45 MX1 (-)
27	Ethernet, LED green, output 3.15 V
28	RJ45 MX1 (+)
29	Power, LED green, output 3.15 V
30	Do not connect (for future use)
31	Power, LED red, output 3.15 V
32	RJ45 MX2 (+)
33	Ethernet, LED red, output 3.15 V
34	RJ45 MX2 (-)
35	Do not connect (for future use)
36	Do not connect (for future use)
37	Do not connect (for future use)
38	RJ45 MX3 (+)
39	Ground (GND)
40	RJ45 MX3 (-)



Design

Lens Mount	No mount
IP code	-
Dimensions H/W/L	84.0 mm x 30.0 mm x 14.3 mm
Mass	26 g
Housing material	-

Features

List of on-camera image pre-processing features.

All features of the table are available via our IDS peak software for image pre-processing on the host computer (sensor model dependent).

GV-5262ACP-M Rev.1.2 (AB11437)

Image Acquisition	Freerun	✓
	Software trigger	✓
	Hardware trigger	✓
	Trigger controlled exposure	✓
	Denoiser	✓
	Long exposure	✓
	Line scan	✓
Flashing	Flashing	✓
	PWM flashing	✓
Image Adjustments	Auto exposure	✓
	Auto gain	✓
	Auto whitebalance	-
	Color correction	-
	Gamma	✓
	LUT	✓
	Mirror/flip	X/Y
On-board Image Processing	Pixel formats	Mono8 Mono10 Mono10p Mono12 Mono12p
	Region of interest	✓
	Decimation (FPGA)	✓
	Decimation (Sensor)	
	Binning (FPGA)	✓
	Binning (Sensor)	
Others	IP settings	✓
	Bandwidth management	✓
	Chunks	✓
	Sequencer	✓
	PTP	✓
	Firmware update	✓
	1st supported firmware version	2.10